



# BUK9640-100A

N-channel TrenchMOS logic level FET

13 March 2014

Product data sheet

## 1. General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

## 2. Features and benefits

- Low conduction losses due to low on-state resistance
- Q101 compliant
- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

## 3. Applications

- 12 V, 24 V and 42 V loads
- Automotive and general purpose power switching
- Motors, lamps and solenoids

## 4. Quick reference data

Table 1. Quick reference data

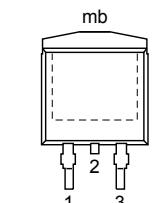
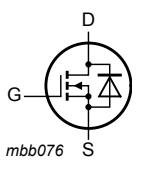
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25^\circ\text{C}$ ; $T_j \leq 175^\circ\text{C}$		-	-	100	V
$I_D$	drain current	$V_{GS} = 5\text{ V}$ ; $T_{mb} = 25^\circ\text{C}$ ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	-	39	A
$P_{tot}$	total power dissipation	$T_{mb} = 25^\circ\text{C}$ ; <a href="#">Fig. 1</a>		-	-	158	W
<b>Static characteristics</b>							
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}$ ; $I_D = 25\text{ A}$ ; $T_j = 25^\circ\text{C}$		-	-	43	$\text{m}\Omega$
		$V_{GS} = 10\text{ V}$ ; $I_D = 25\text{ A}$ ; $T_j = 25^\circ\text{C}$		-	29	39	$\text{m}\Omega$
		$V_{GS} = 5\text{ V}$ ; $I_D = 25\text{ A}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 11</a> ; <a href="#">Fig. 12</a>		-	34	40	$\text{m}\Omega$
<b>Dynamic characteristics</b>							
$Q_{GD}$	gate-drain charge	$V_{GS} = 5\text{ V}$ ; $I_D = 25\text{ A}$ ; $V_{DS} = 80\text{ V}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 13</a>		-	20	-	nC

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Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Avalanche ruggedness</b>							
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 39 \text{ A}$ ; $V_{sup} \leq 100 \text{ V}$ ; $R_{GS} = 50 \Omega$ ; $V_{GS} = 5 \text{ V}$ ; $T_{j(init)} = 25 \text{ }^\circ\text{C}$ ; unclamped		-	-	182	mJ

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain[1]		
3	S	source		
mb	D	mounting base; connected to drain	 <b>D2PAK (SOT404)</b>	

[1] It is not possible to make a connection to pin 2.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9640-100A	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9640-100A	BUK9640-100A

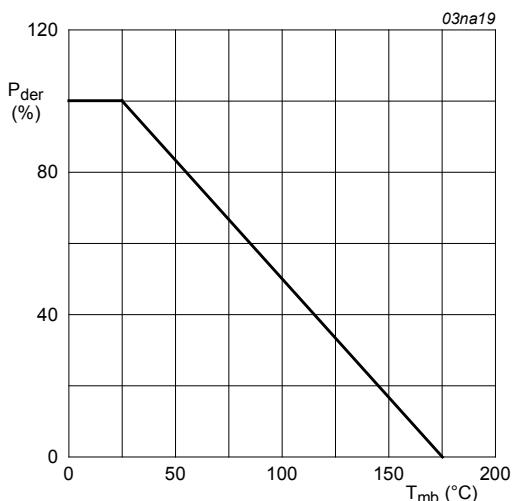
## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

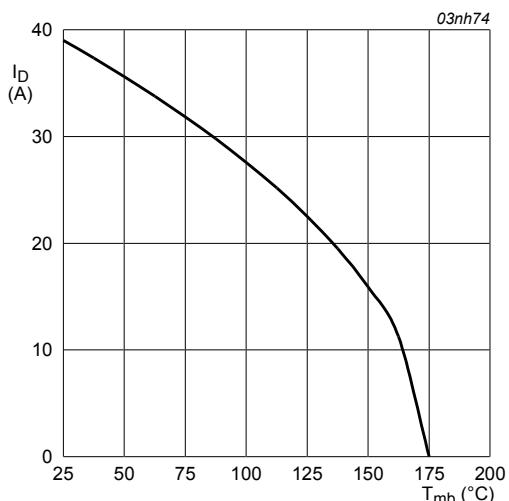
Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25 \text{ }^\circ\text{C}$ ; $T_j \leq 175 \text{ }^\circ\text{C}$		-	100	V
$V_{DGR}$	drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega$		-	100	V
$V_{GS}$	gate-source voltage			-15	15	V

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <a href="#">Fig. 1</a>	-	158	W
I <sub>D</sub>	drain current	T <sub>mb</sub> = 25 °C; V <sub>GS</sub> = 5 V; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	39	A
		T <sub>mb</sub> = 100 °C; V <sub>GS</sub> = 5 V; <a href="#">Fig. 2</a>	-	28	A
I <sub>DM</sub>	peak drain current	T <sub>mb</sub> = 25 °C; pulsed; t <sub>p</sub> ≤ 10 µs; <a href="#">Fig. 3</a>	-	159	A
T <sub>stg</sub>	storage temperature		-55	175	°C
T <sub>j</sub>	junction temperature		-55	175	°C
<b>Source-drain diode</b>					
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	-	39	A
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 µs; T <sub>mb</sub> = 25 °C	-	159	A
<b>Avalanche ruggedness</b>					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	I <sub>D</sub> = 39 A; V <sub>sup</sub> ≤ 100 V; R <sub>GS</sub> = 50 Ω; V <sub>GS</sub> = 5 V; T <sub>j(init)</sub> = 25 °C; unclamped	-	182	mJ



**Fig. 1.** Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot}(25^{\circ}\text{C})} \times 100 \%$$



**Fig. 2.** Normalized continuous drain current as a function of mounting base temperature

T<sub>amb</sub> = 25 °C; I<sub>DM</sub> is single pulse

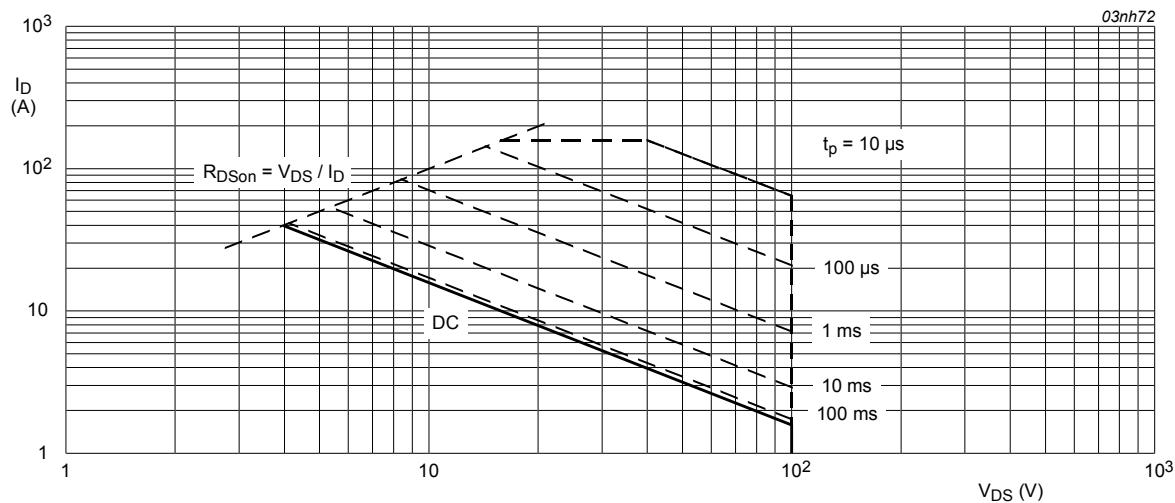


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{amb} = 25^\circ C$ ;  $I_{DM}$  is single pulse

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 4</a>	-	-	0.95	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	mounted on a printed-circuit board; minimum footprint	-	50	-	K/W

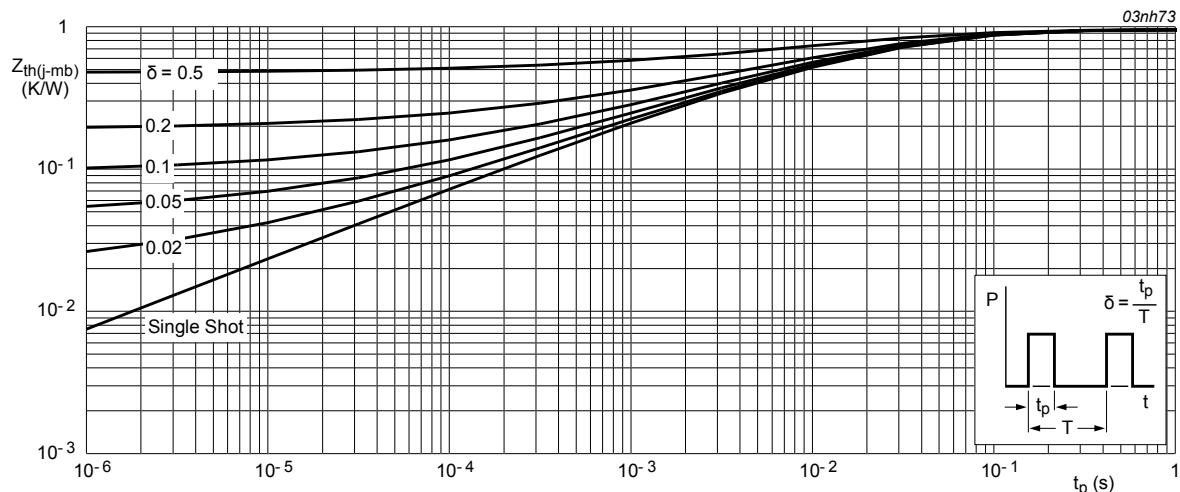


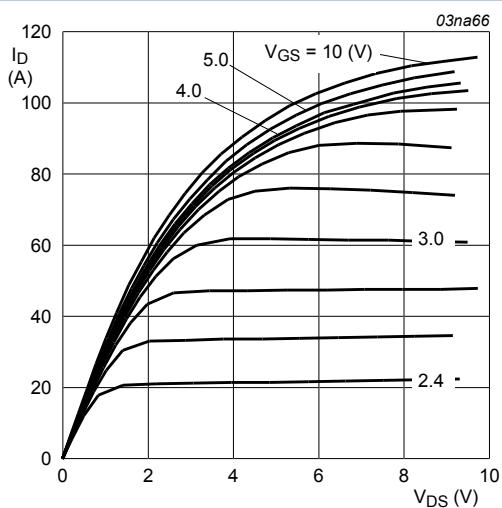
Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

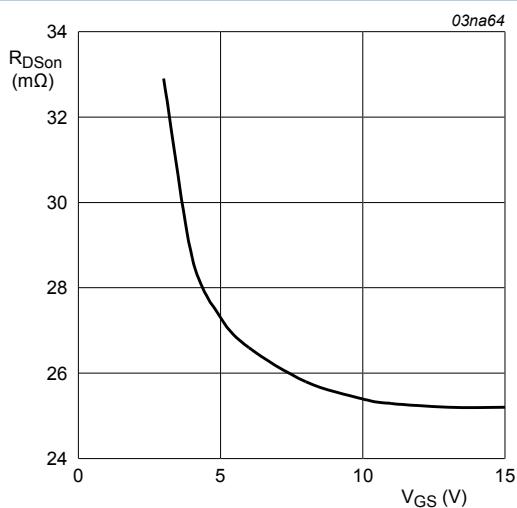
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		100	-	-	V
		I <sub>D</sub> = 0.25 mA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = -55 °C		89	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>		1	1.5	2	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 175 °C; <a href="#">Fig. 10</a>		0.5	-	-	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = -55 °C; <a href="#">Fig. 10</a>		-	-	2.3	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 100 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C		-	-	500	µA
		V <sub>DS</sub> = 100 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	0.05	10	µA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	2	100	nA
		V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	2	100	nA
R <sub>DSON</sub>	drain-source on-state resistance	V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C		-	-	43	mΩ
		V <sub>GS</sub> = 5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 175 °C; <a href="#">Fig. 11</a> ; <a href="#">Fig. 12</a>		-	-	100	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C		-	29	39	mΩ
		V <sub>GS</sub> = 5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a> ; <a href="#">Fig. 12</a>		-	34	40	mΩ
<b>Dynamic characteristics</b>							
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 25 A; V <sub>DS</sub> = 80 V; V <sub>GS</sub> = 5 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 13</a>		-	48	-	nC
Q <sub>GS</sub>	gate-source charge			-	5.4	-	nC
Q <sub>GD</sub>	gate-drain charge			-	20	-	nC
C <sub>iss</sub>	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 25 V; f = 1 MHz; T <sub>j</sub> = 25 °C; <a href="#">Fig. 14</a>		-	2304	3072	pF
C <sub>oss</sub>	output capacitance			-	222	266	pF
C <sub>rss</sub>	reverse transfer capacitance			-	151	207	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = 30 V; R <sub>L</sub> = 1.2 Ω; V <sub>GS</sub> = 5 V; R <sub>G(ext)</sub> = 10 Ω; T <sub>j</sub> = 25 °C		-	20	-	ns
t <sub>r</sub>	rise time			-	135	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	125	-	ns
t <sub>f</sub>	fall time			-	90	-	ns
L <sub>D</sub>	internal drain inductance	from upper edge of drain mounting base to centre of die; T <sub>j</sub> = 25 °C		-	2.5	-	nH

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		from drain lead 6 mm from package to centre of die; $T_j = 25^\circ\text{C}$		-	4.5	-	nH
$L_s$	internal source inductance	from source lead to source bond pad; $T_j = 25^\circ\text{C}$		-	7.5	-	nH
<b>Source-drain diode</b>							
$V_{SD}$	source-drain voltage	$I_S = 25\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 15</a>		-	0.85	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 37\text{ A}$ ; $dI_S/dt = -100\text{ A}/\mu\text{s}$		-	60	-	ns
$Q_r$	recovered charge	$V_{GS} = -10\text{ V}$ ; $V_{DS} = 30\text{ V}$ ; $T_j = 25^\circ\text{C}$		-	240	-	nC



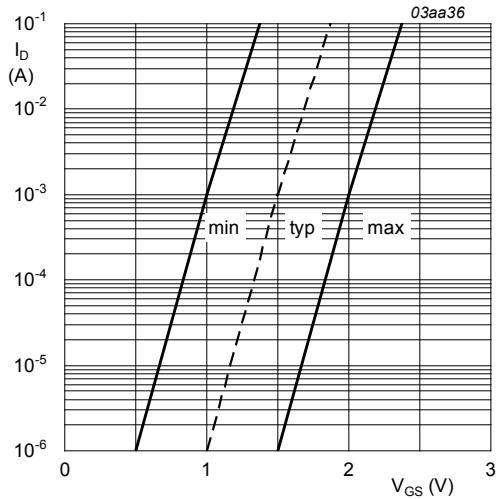
**Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values**

$T_j = 25^\circ\text{C}$ ;  $t_p = 300\mu\text{s}$



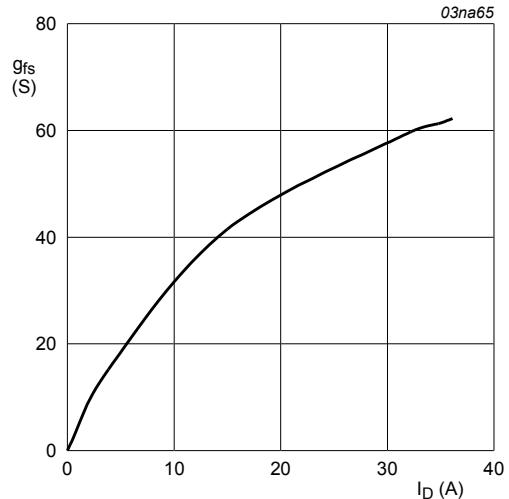
**Fig. 6. Drain-source on-state resistance as a function of gate-source voltage; typical values**

$T_j = 25^\circ\text{C}$ ;  $I_D = 25\text{A}$



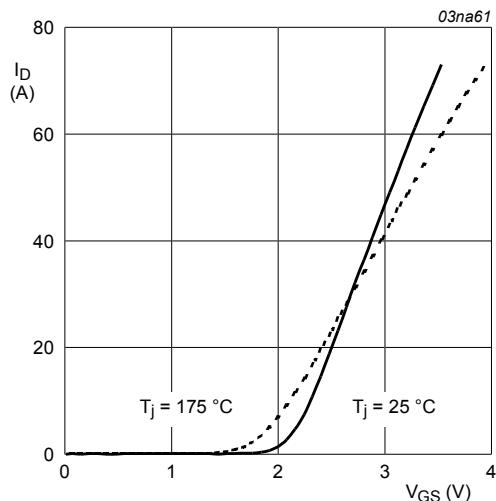
$T_j = 25^\circ\text{C}$ ;  $V_{DS} = 5\text{ V}$

**Fig. 7. Sub-threshold drain current as a function of gate-source voltage**



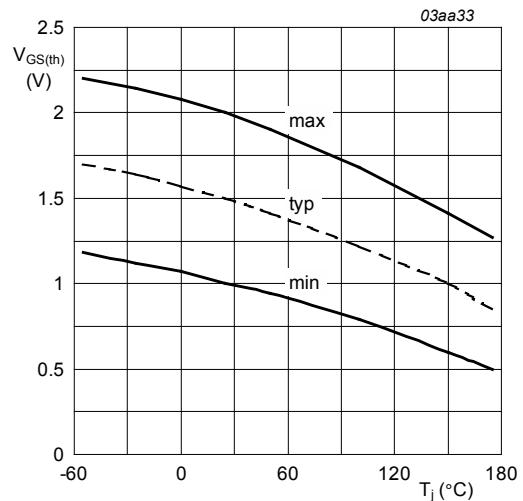
**Fig. 8. Forward transconductance as a function of drain current; typical values**

$T_j = 25^\circ\text{C}$ ;  $V_{DS} = 25\text{ V}$



$V_{DS} = 25\text{ V}$

**Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



$I_D = 1\text{ mA}$ ;  $V_{DS} = V_{GS}$

**Fig. 10. Gate-source threshold voltage as a function of junction temperature**

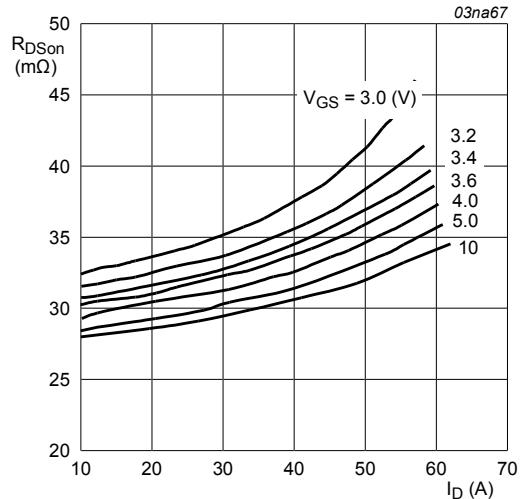


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

$T_j = 25^\circ\text{C}$

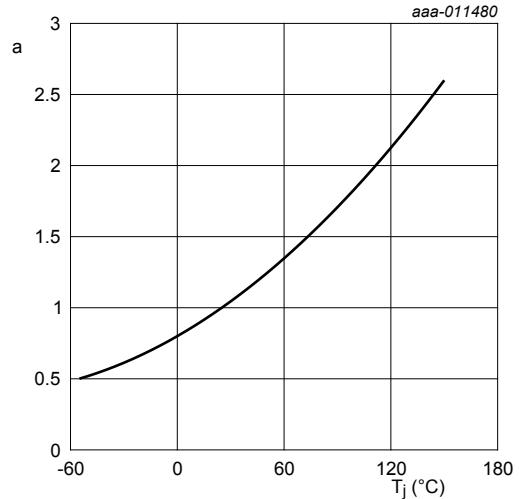


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

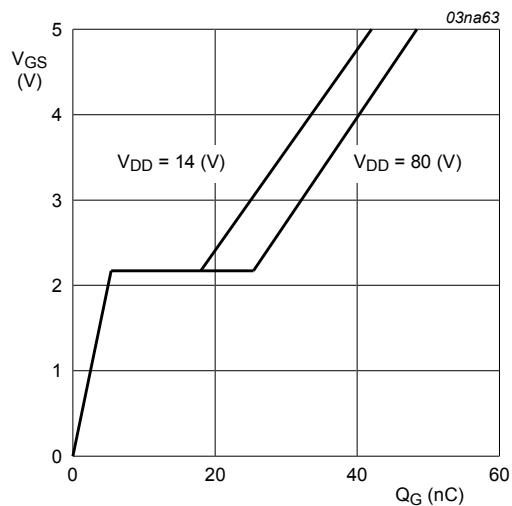


Fig. 13. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^\circ\text{C}; I_D = 25\text{A}$

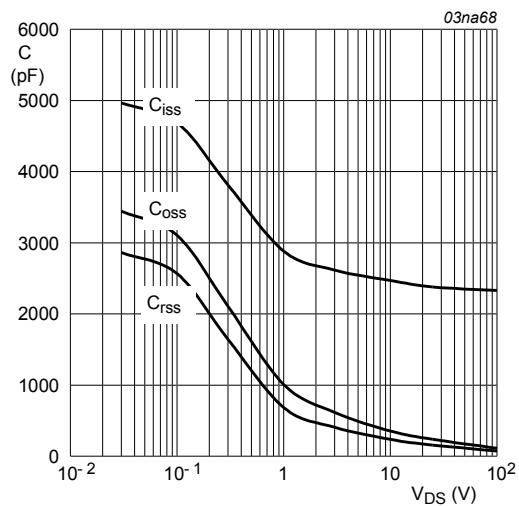


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0\text{V}; f = 1\text{MHz}$

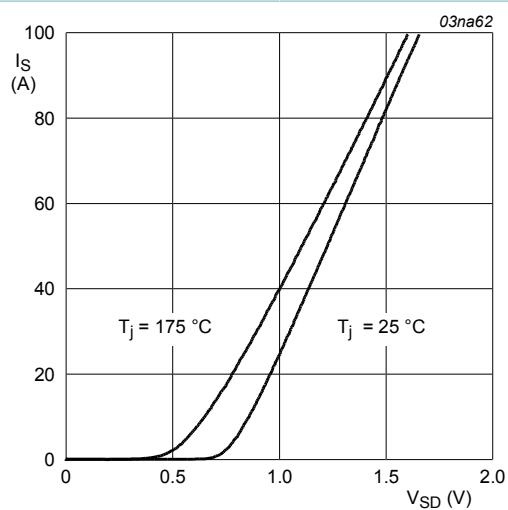


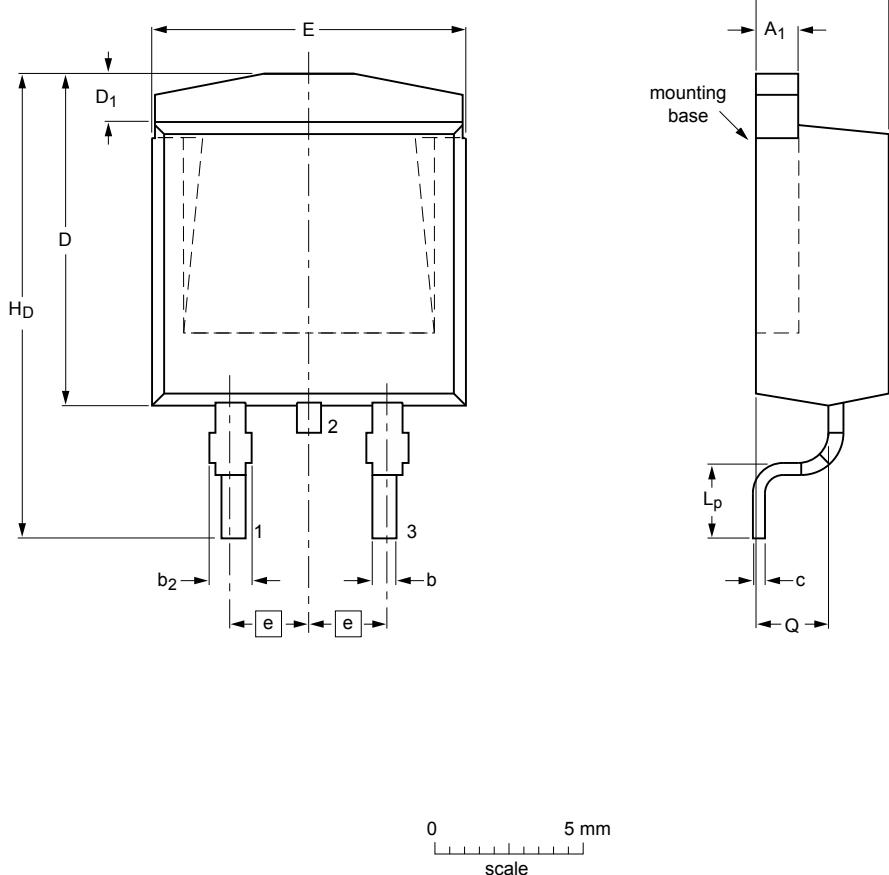
Fig. 15. Source current as a function of source-drain voltage; typical values

$$V_{GS} = 0V$$

## 11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>2</sub>	c	D	D <sub>1</sub>	E	e	H <sub>D</sub>	L <sub>p</sub>	Q
mm	max	4.5	1.40	0.85	1.45	0.64	11	1.6	10.3	15.8	2.9	2.6
	nom								2.54			
	min	4.1	1.27	0.60	1.05	0.46		1.2	9.7	14.8	2.1	2.2

sot404\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT404						-06-03-16- 13-02-25

Fig. 16. Package outline D2PAK (SOT404)

## 12. Legal information

### 12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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